



2816
2816-12-12-07

Patent

Docket No.: LWM-A110

Information Disclosure Statement Transmittal

I hereby certify that this transmittal of the below described document is being deposited with the United States Postal Service in an envelope bearing First Class Postage and addressed to the Commissioner of Patents and Trademarks, Washington, D.C., 20231, on the below date of deposit.			
Date of Deposit:	10/04/01	Name of Person Making the Deposit:	Julie Gibson
		Signature of the Person Making the Deposit:	<i>Julie Gibson</i>

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor(s): Pamela S. Trammel, Jonathan G. Bornstein and David H. Menche

Serial No.: 09/940,567

Group Art Unit:

Filed: 08/27/01

Examiner:

Title: A PLANAR LIGHTWAVE CIRCUIT ACTIVE DEVICE METALLIZATION PROCESS

The Commissioner of Patents and Trademarks
Washington, D.C. 20231
Sir:

Information Disclosure Statement Transmittal

Transmitted herewith is the following:

- Formal drawings, totaling sheets.
- Informal drawings, totaling sheets.
- Certification for PTO Consideration
- ☒ Information Disclosure statement (2 sheets)
- Information Disclosure statement and late filing fee
- ☒ Form 1449
- Petition for Extension of Time
- ☒ Other: References

Fee Calculation (for other than a small entity)				
Fee Items			Fee Rate	Total
Petition for Extension of Time (fee calculated elsewhere)			\$.00	
Information Disclosure Statement, late filing			\$240.00	
Other:				
Total Fees				

PAYMENT OF FEES

1. The full fee due in connection with this communication is provided as follows:
 - ☒ The Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment to Deposit Account No.: 23-0085.
A duplicate copy of this authorization is enclosed.
 - ☐ A check in the amount of \$
 - ☐ Charge any fees required or credit any overpayments associated with this filing to Deposit Account No.: 23-0085.

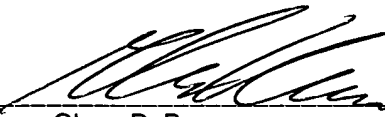
Please direct all correspondence concerning the above-identified application to the following address:

WAGNER, MURABITO & HAO LLP
Two North Market Street, Third Floor
San Jose, California 95113
(408) 938-9060

Respectfully submitted,

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Date: 12/4/01

By: 
Glenn D. Barnes
Reg. No. 42,293



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney Docket No.: LWM-A110

Inventor(s): Pamela S. Trammel, Jonathan G. Bornstein and David H. Menche

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Sir:

Information Disclosure Statement Submitted Pursuant to 37 C.F.R. 1.97(b)

The citations referenced herein, copies attached, may be material to the examination of the above-identified application and are, therefore, submitted in compliance with the duty of disclosure as defined in 37 C.F.R. 1.56. The Examiner is requested to make these citations of official record in the application.

This Information Disclosure Statement submitted in accordance with 37 C.F.R. 1.97(b) is not to be construed as a representation that a search has been made, that additional items material to the examination of this application do not exist, or that any one or more of these citations constitute prior art under 35 U.S.C. 102.

The Examiner's attention is respectfully directed to the following U.S. Patents:

<u>Pat. No.</u>	<u>Pat. Title</u>	<u>Grant Date</u>
4,489,742	THERMOELECTRIC DEVICE AND METHOD OF MAKING AND USING SAME	12/25/84
4,983,225	PROCESS OF MANUFACTURING MINIATURE THERMOELECTRIC CONVERTERS	01/08/91
5,231,054	METHOD OF FORMING CONDUCTIVE MATERIAL SELECTIVELY	07/27/93
5,877,045	METHOD OF FORMING A PLANAR SURFACE DURING MULTI-LAYER INTER-CONNECT FORMATION BY A LASER-ASSISTED DIELECTRIC DEPOSITION	03/02/99
5,877,045	METHOD OF FORMING A PLANAR SURFACE DURING MULTI-LAYER INTERCONNECT FORMATION BY A LASER-ASSISTED DIELECTRIC DEPOSITION	03/02/99
6,083,770	THERMOELECTRIC PIECE AND PROCESS OF MAKING THE SAME	07/04/00
6,100,199	EMBEDDED THERMAL CONDUCTORS FOR SEMICONDUCTOR CHIPS	08/08/00
6,171,879	METHODS OF FORMING THERMO-MECHANICAL SENSOR	01/09/01
6,259,350	SENSOR AND METHOD FOR MANUFACTURING A SENSOR	07/10/01
4,867,842	METHOD OF MAKING SLOTTED DIAPHRAGM SEMICONDUCTOR DEVICES	09/19/89
4,571,608	INTEGRATED VOLTAGE-ISOLATION POWER SUPPLY	02/18/86
4,472,239	METHOD OF MAKING SEMICONDUCTOR DEVICE	09/18/84

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